



News Release

FOR IMMEDIATE RELEASE

Elpida Unveils Industry's First 2-Gigabit DDR2 Mobile RAM

Operates at 800Mbps at 1.2V and 1/16th the standby power consumption of DDR2

TOKYO, JAPAN, September 28, 2009 – Elpida Memory, Inc. (TOKYO: 6665), Japan's leading global supplier of Dynamic Random Access Memory (DRAM), today announced that it had developed the industry's first 2-gigabit DDR2 Mobile RAM™.

The new 2-Gigabit Mobile RAM features the highest density for a JEDEC LPDDR2 (DDR2 Mobile RAM) compatible device.

Elpida has leveraged its low voltage and low-power consumption technology to achieve a device that can operate at 1.2V (conventional DDR Mobile RAM requires 1.8V) while achieving a high-speed data transfer rate of 800Mbps (DDR Mobile RAM is 400Mbps). Also, compared with other same-density and same-speed DDR2 products, as little as 1/16th the power consumption is needed when on standby, making it an eco-friendly DRAM.

Because of its high density, low power consumption and high-speed functionality the new device is likely to make a powerful contribution to the development of innovative mobile applications for high-end mobile phones and smart phones and in such areas as the growing market for Netbooks and MID (Mobile Internet Devices).

The new device can meet a variety of customer needs. It can be shipped as a bare chip for use in SiP (System in Package), MCP (Multi-chip Package) and other multi-layer packages or it can be packaged for a PoP (Package on Package) configuration to enable space-saving features.

Sample shipments are expected to begin in October, 2009 with the start-up of mass production scheduled for the first half of 2010.

Features of the 2-Gigabit DDR2 Mobile RAM

Product process	50nm CMOS
Data width	×16-bit / ×32-bit
Per pin data transfer rate	800Mbps 667Mbps
Supply voltage	VDD1: 1.8V, VDD2/VDDCA/VDDQ: 1.2V
Operating temperature range (TC)	-25 to 85°C (standard), -25 to 105°C (extended temperature range)
Shipment configuration	Bare chip (JEDEC compatible) 168-ball PoP-type FBGA (JEDEC compatible) 216-ball PoP-type FBGA (JEDEC compatible)

About Elpida

Elpida Memory, Inc. (Tokyo: 6665) is a leading manufacturer of Dynamic Random Access Memory (DRAM) integrated circuits. The company's design, manufacturing and sales operations are backed by world class technological expertise. Its 300mm manufacturing facilities, consisting of its Hiroshima Plant and a Taiwan-based joint venture, Rexchip Electronics, utilize the most advanced manufacturing technologies available. Elpida's portfolio features such characteristics as high-density, high-speed, low power and small packaging profiles. The company provides DRAM solutions across a wide range of applications, including high-end servers, mobile phones and digital consumer electronics. More information can be found at <http://www.elpida.com>.

Mobile RAM is a trademark of Elpida Memory, Inc.

Information in this news release is current as of the timing of the release, but may be revised later without notice.

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